Use hot-melt technology to redesign packaging

TOYOMELT® H, ER, HM, P series
LABELMELT® BL series

Hot-melt adhesives TOYOMELTTM H, ER, HM, P series , LABELMELTTM BL series

- **Contribute to save resources - 100% solid formula, no solvent, No drying process**
- **Original quality control technique gives an adhesion process optimization**

Core solution areas








Technology elements

Core technologies	Customer benefits
Resin formulation	Tailored elasticity from bonding to pressure-sensitive adhesion
Release control	Tailored peel response for each application
Alkali solubility	Easy disassembly and release improve recyclability
UV crosslinking	Heat resistance at 120% of our conventional product
Joining different materials	Compatible with PET/PP, metal/resin and other material combinations

Co-creating tomorrow's standards

bonding layers	Solutions
For composite materials as a base resin	Functional additive formulation and resin modification (bonding + more; basecoat + more; sealing + more)
To replace existing bonding methods	Use our adhesive expertise and core technology for material design (replace solvent-based adhesives; bond porous substrates)
For removable as a base resin	Apply proprietary formulation technology (alkaline release or release at a set temperature)

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